

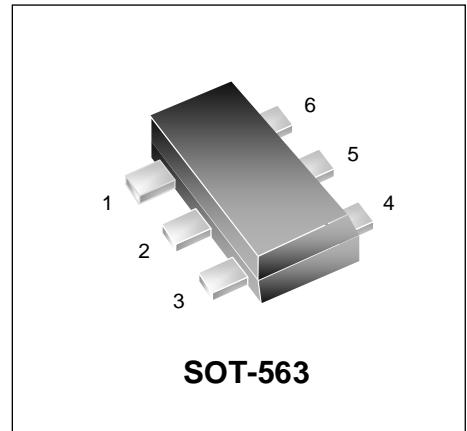


WM02DH08T

N+P Dual Channel MOSFET

Features

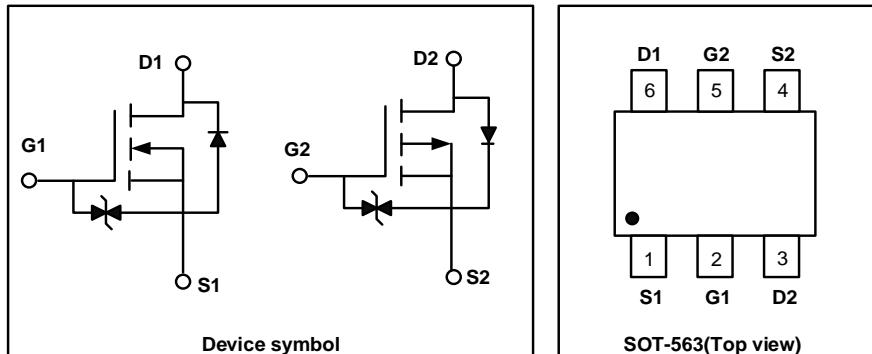
- N - Channel:
 $V_{DS} = 20V$, $I_D = 0.75A$
 $R_{DS(on)} < 0.38\Omega$ @ $V_{GS} = 4.5V$
 $R_{DS(on)} < 0.45\Omega$ @ $V_{GS} = 2.5V$
- P - Channel:
 $V_{DS} = -20V$, $I_D = -0.66A$
 $R_{DS(on)} < 0.52\Omega$ @ $V_{GS} = -4.5V$
 $R_{DS(on)} < 0.70\Omega$ @ $V_{GS} = -2.5V$
- ESD Protected



Mechanical Characteristics

- SOT-563 Package
- Marking : Making Code
- RoHS Compliant

Schematic & PIN Configuration



Absolute Maximum Ratings

Parameter	Symbol	Value		Unit
Drain-Source Voltage	V_{DSS}	20	-20	V
Gate-Source Voltage	V_{GSS}	± 12	± 12	
Continuous Drain Current	I_D	0.75	-0.66	A
Pulsed Drain Current ²	I_{DM}	1.8	-1.2	
Power Dissipation	P_D	290	290	mW
Thermal Resistance from Junction to Ambient ¹	$R_{\theta JA}$	430		°C/W
Junction Temperature	T_J	150		°C
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150		°C

Electrical Characteristics N-Channel ($T_{amb}=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0 \text{ V}, I_D = 250\mu\text{A}$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{V}, V_{GS} = 0 \text{ V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10\text{V}$	-	-	± 20	μA
Drain-Source on-State Resistance ³	$R_{DS(on)}$	$V_{GS} = 4.5\text{V}, I_D = 0.65\text{A}$	-	0.19	0.38	Ω
		$V_{GS} = 2.5\text{V}, I_D = 0.55\text{A}$	-	0.26	0.45	
		$V_{GS} = 1.8\text{V}, I_D = 0.45\text{A}$	-	0.39	-	
Gate Threshold Voltage ³	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.35	0.75	1.1	V
Forward Transconductance	g_{fs}	$V_{DS} = 10\text{V}, I_D = 0.80\text{A}$	-	1.6	-	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = 16\text{V}, f = 1\text{MHz}$	-	55	-	pF
Output Capacitance	C_{oss}		-	11	-	
Reverse Transfer Capacitance	C_{rss}		-	8	-	
Switching Characteristics						
Turn-on Delay Time ⁴	$t_{d(on)}$	$V_{DS} = 10\text{V}, V_{GS} = 4.5\text{V}, I_D = 0.5\text{A}, R_{GEN} = 10\Omega$	-	6.7	-	ns
Turn-on Rise Time ⁴	t_r		-	4.8	-	
Turn-off Delay Time ⁴	$t_{d(off)}$		-	17.3	-	
Turn-off Fall Time ⁴	t_f		-	7.4	-	
Source-Drain Diode Characteristics						
Body Diode Voltage ³	V_{SD}	$I_S = 0.15\text{A}, V_{GS} = 0\text{V}$	-	-	1.2	V

Electrical Characteristics P-Channel ($T_{amb}=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0 \text{ V}, I_D = -250\mu\text{A}$	-20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{V}, V_{GS} = 0 \text{ V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10\text{V}$	-	-	± 20	μA
Drain-Source On-state Resistance ³	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}, I_D = -0.66\text{A}$	-	0.45	0.52	Ω
		$V_{GS} = -2.5\text{V}, I_D = -0.60\text{A}$	-	0.68	0.78	
		$V_{GS} = -1.8\text{V}, I_D = -0.50\text{A}$	-	0.95	-	
Gate Threshold Voltage ³	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.3	-0.6	-1.1	V
Forward transconductance	g_{fs}	$V_{DS} = 10\text{V}, I_D = -0.54\text{A}$	-	1.2	-	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = -16\text{V}, f = 1\text{MHz}$	-	77	-	pF
Output Capacitance	C_{oss}		-	15	-	
Reverse Transfer Capacitance	C_{rss}		-	9	-	
Switching Characteristics						
Turn-on Delay Time ⁴	$t_{d(on)}$	$V_{DS} = -10\text{V}, V_{GS} = -4.5\text{V}, I_D = -0.2\text{A}, R_G = 10\Omega$	-	9	-	ns
Turn-on Rise Time ⁴	t_r		-	5.7	-	
Turn-off Delay Time ⁴	$t_{d(off)}$		-	32.6	-	
Turn-off Fall Time ⁴	t_f		-	20.3	-	
Source-Drain Diode Characteristics						
Body Diode Voltage ³	V_{SD}	$I_S = -0.5\text{A}, V_{GS} = 0\text{V}$	-	-	-1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. For a device mounted on 25mm X 25mm FR-4 PCB board with a high coverage of single sided 1oz copper, in still air conditions with two active die.
3. Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

Typical Characteristics: N-CHANNEL

Figure 1. Output Characteristics

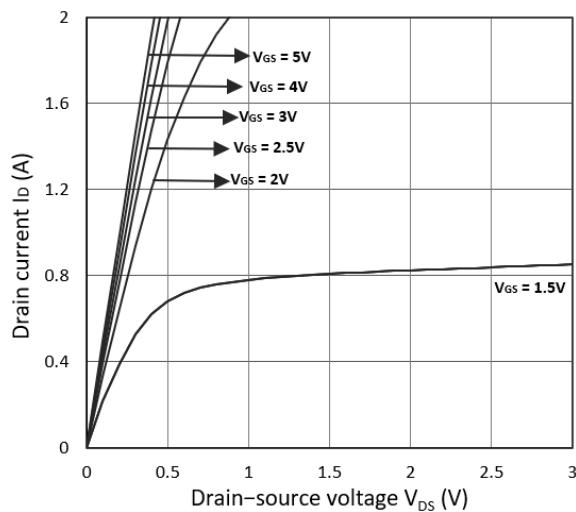


Figure 2. Transfer Characteristics

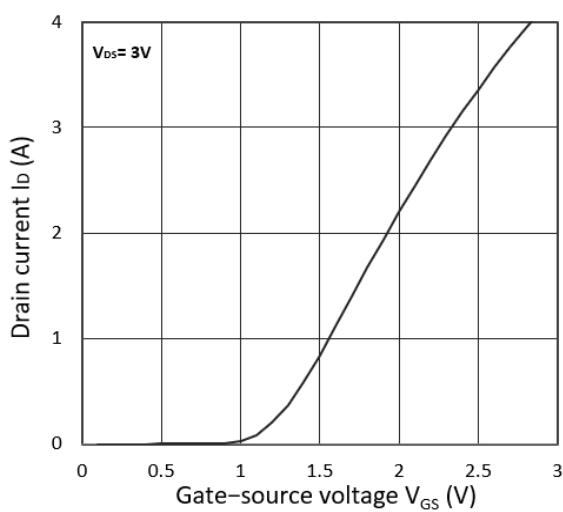
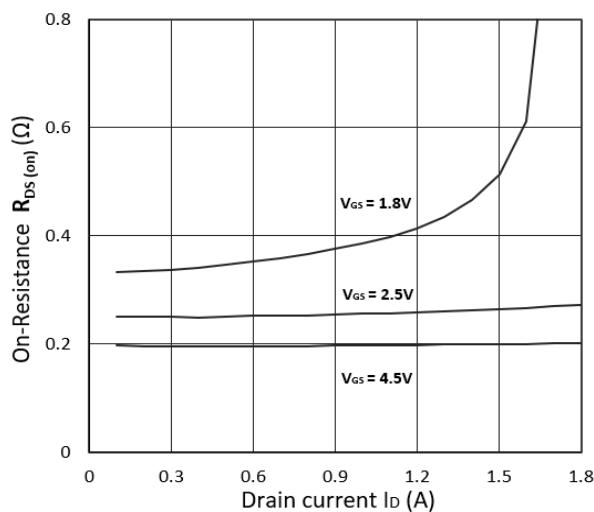
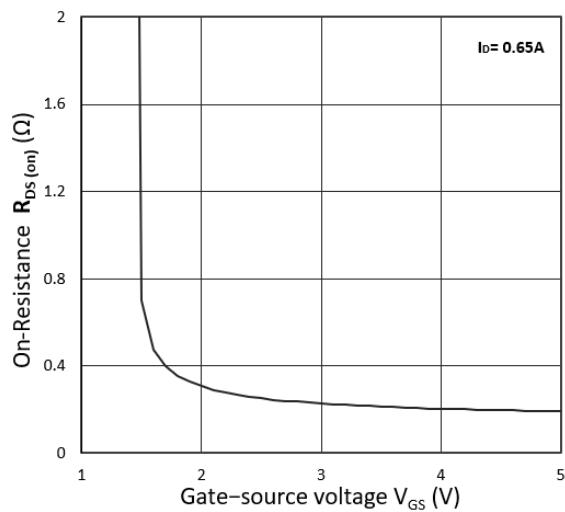
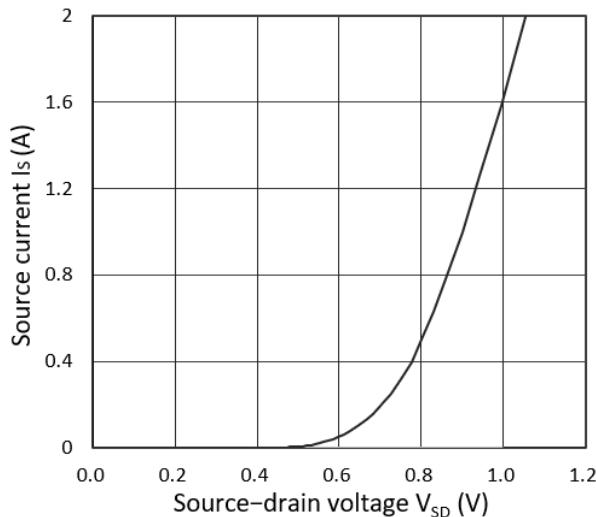
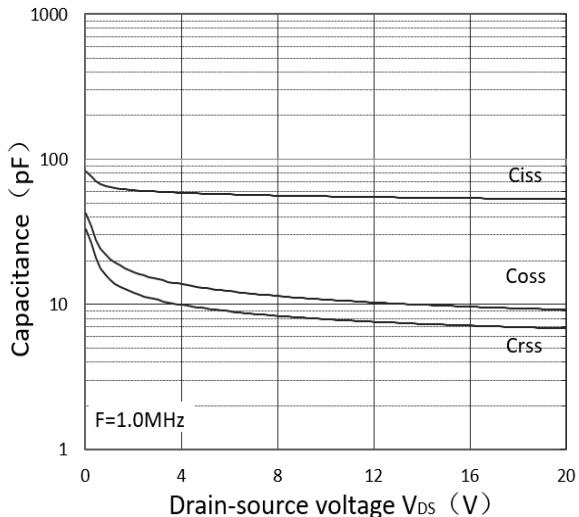
Figure 3. $R_{DS(ON)}$ vs. I_D Figure 4. $R_{DS(ON)}$ vs. V_{GS} Figure 5. I_S vs. V_{SD} 

Figure 6. Capacitance Characteristics



Typical Characteristics: P-CHANNEL

Figure 1. Output Characteristics

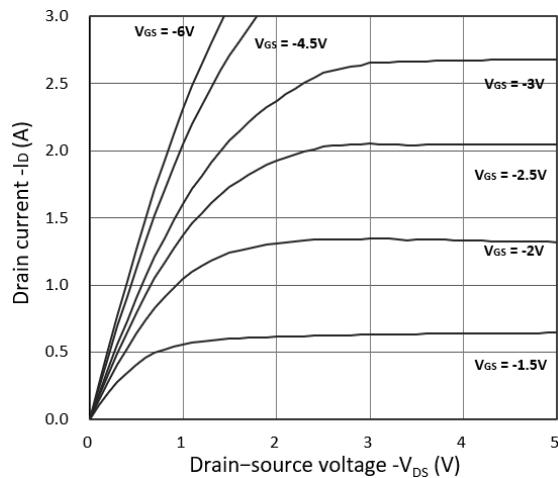


Figure 2. Transfer Characteristics

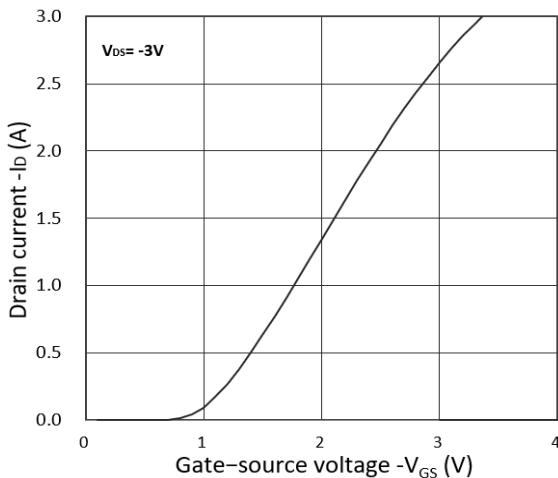
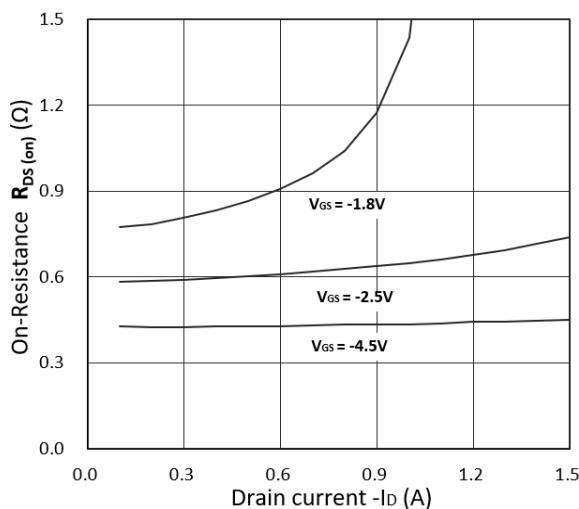
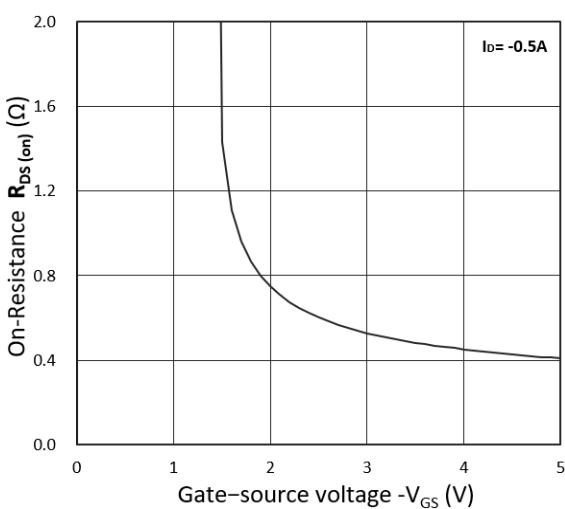
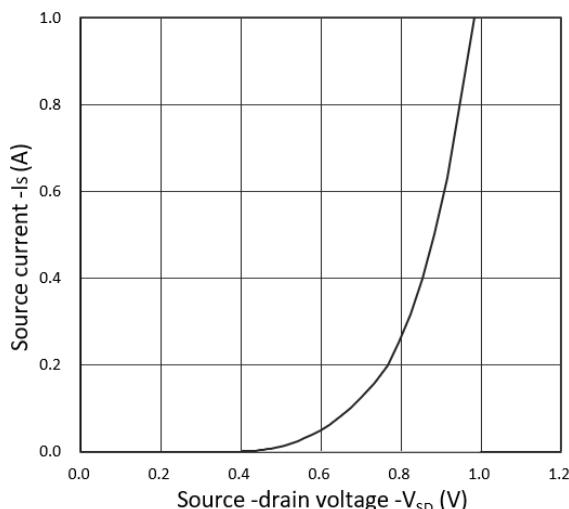
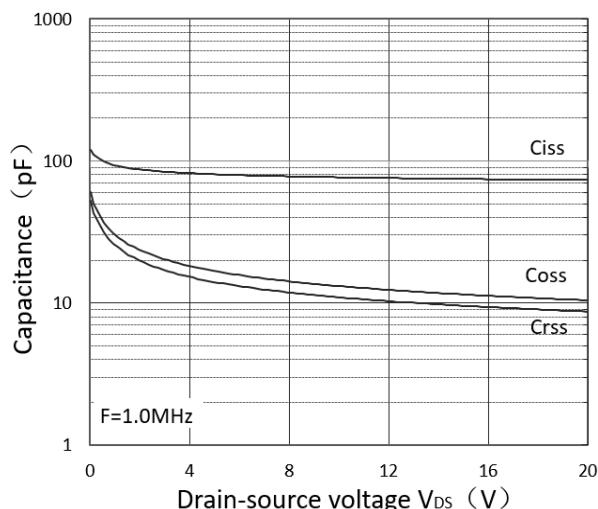
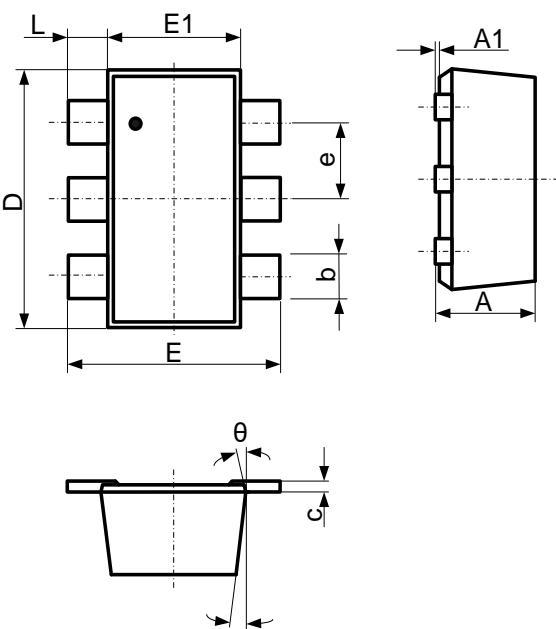
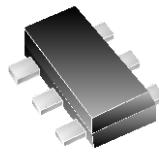
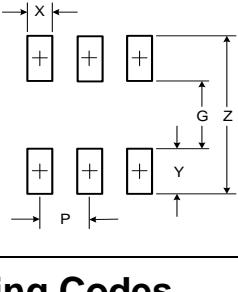
Figure 3. $R_{DS(ON)}$ vs. I_D Figure 5. I_S vs. V_{SD} 

Figure 6. Capacitance Characteristics



Outline Drawing – SOT-563

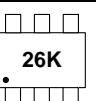
PACKAGE OUTLINE		SOT-563			
		 SOT-563			
SYMBOL	INCHES		MILLIMETER		
	MIN	MAX	MIN	MAX	
A	0.021	0.024	0.525	0.600	
A1	0.000	0.002	0.000	0.050	
e	0.018	0.022	0.450	0.550	
c	0.004	0.006	0.090	0.160	
D	0.059	0.067	1.500	1.700	
b	0.007	0.011	0.170	0.270	
E1	0.043	0.051	1.100	1.300	
E	0.059	0.067	1.500	1.700	
L	0.004	0.012	0.100	0.300	
θ	7°REF		7°REF		

		DIMENSIONS	
DIM	INCHES	MILLIMETERS	
Z	0.0752	1.91	
G	0.0350	0.89	
P	0.020TYP	0.51 TYP	
X	0.0118	0.3	
Y	0.0201	0.51	

Notes

1. Dimensioning and tolerances per ANSI Y14.5M, 1985.
2. Controlling Dimension: Inches
3. Dimensions are exclusive of mold flash and metal burrs.

Marking Codes

Part Number	WM02DH08T
Marking Code	

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.



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Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.